## (2) additive <br> electronics

EMPOWERING 3D-printing for future electronics manufacturing

## The Project

Problem: further of

Solution: orm embedding designs of the outer structure and internal electronics, supports of components and increases miniaturization.

Stage 1: R\&D prototyping of electronic applications Stage 2: low volume electronics manufacturing across various industries

Fraunhofer technology: Hybrid process chain and corresponding process strategies for additively manufactured electronics.

## The Team

Location: Fraunhofer IPA, Stuttgart / additive electronics GmbH, Gmund
Members: Wissenschaftler) (Wissenschaftler)
ae: Felix Michl (CEO); Florian Vetter (CCO); Jorin Dinter (COO)

AHEAD Infos Batch: 2022/23
Phase: 1 Track: Spin-off

## The Business Model



## The Side Facts

## Customer Focus: <br> B2B

Searching For: PoC partner, expertise, research partner, investors,

Industry Tags: Materials, industrial goods and services, (semiconductors and semiconductor equipment), technology hardware \& equipment

Technology Tags: 3D printing, additive manufacturing, new materials, customization, PCB prototyping, last mile solution, sensors, zero waste, smart factory

